

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

### Product Summary

**RoHS**

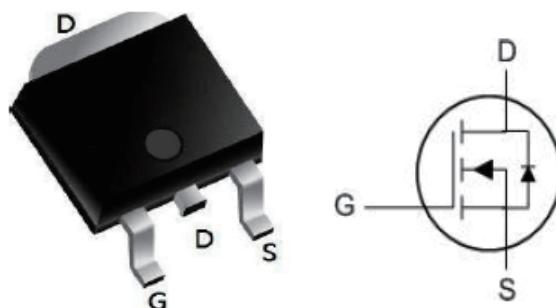
BVDSS	RDSON	ID
30V	6.5mΩ	60A

### Description

The 60N03 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 60N03 meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

### TO252 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
$V_{DS}$	Drain-Source Voltage	30		V
$V_{GS}$	Gate-Source Voltage	$\pm 20$		V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	60		A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	33		A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	198		A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	36		mJ
$I_{AS}$	Avalanche Current	53.8		A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	32.5		W
$T_{STG}$	Storage Temperature Range	-55 to 175		°C
$T_J$	Operating Junction Temperature Range	-55 to 175		°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{eJC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	3.56	°C/W

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\ \mu\text{A}$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V},$	-	-	1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$	1	1.5	2.5	V
$R_{DS(\text{on})}$ note <sup>3</sup>	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	-	6.5	7.5	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	-	10	14	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	1140	-	pF
$C_{oss}$	Output Capacitance		-	175	-	
$C_{rss}$	Reverse Transfer Capacitance		-	151	-	
$Q_g$	Total Gate Charge	$V_{DS}=15\text{V}, I_D=25\text{A}, V_{GS}=10\text{V}$	-	13.3	-	nC
$Q_{gs}$	Gate-Source Charge		-	3.1	-	
$Q_{gd}$	Gate-Drain( "Miller" ) Charge		-	5	-	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D=25\text{A}, R_{GEN}=3\ \Omega, V_{GS}=10\text{V}$	-	15	-	ns
$t_r$	Turn-on Rise Time		-	19	-	
$t_{d(off)}$	Turn-off Delay Time		-	35	-	
$t_f$	Turn-off Fall Time		-	21	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	50	-	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	200	-	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_s=30\text{A}$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	-	-	25	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=30\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	26	-	nC

Note :

- 1.Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2.EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=15\text{V}, V_G=10\text{V}, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=12\text{A}$
- 3.Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

### Typical Performance Characteristics

Figure 1: Output Characteristics

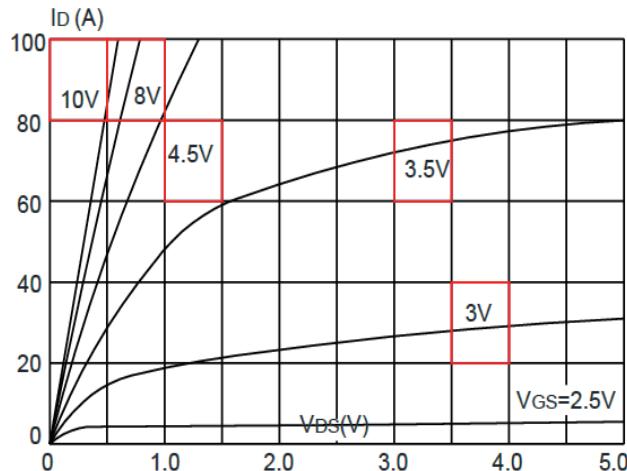


Figure 2: Typical Transfer Characteristics

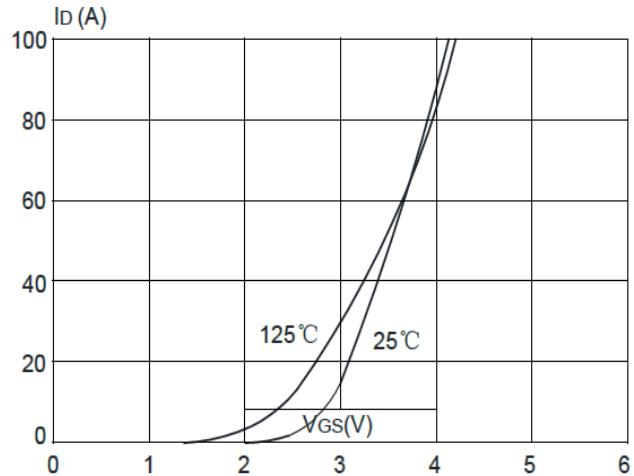


Figure 3: On-resistance vs. Drain Current

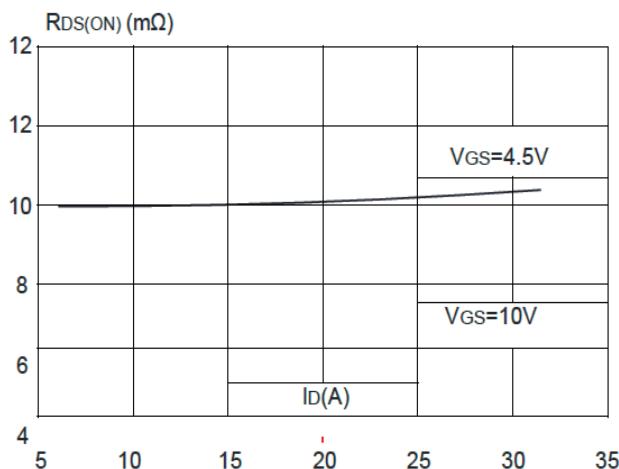


Figure 4: Body Diode Characteristics

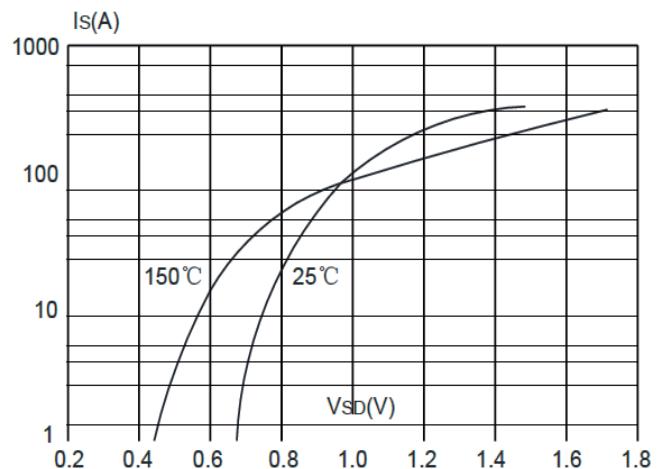


Figure 5: Gate Charge Characteristics

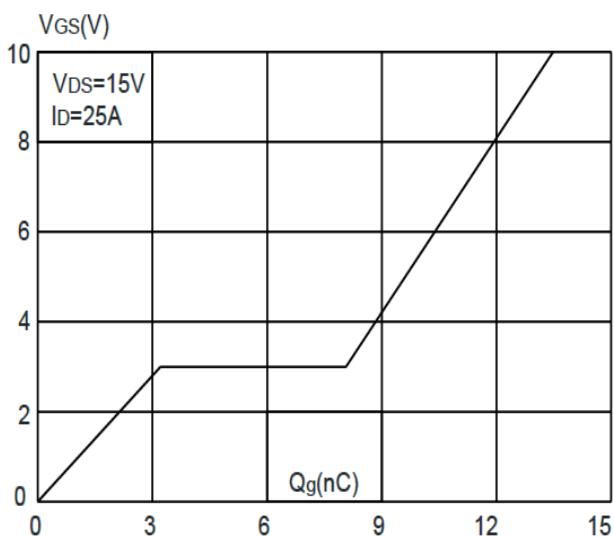
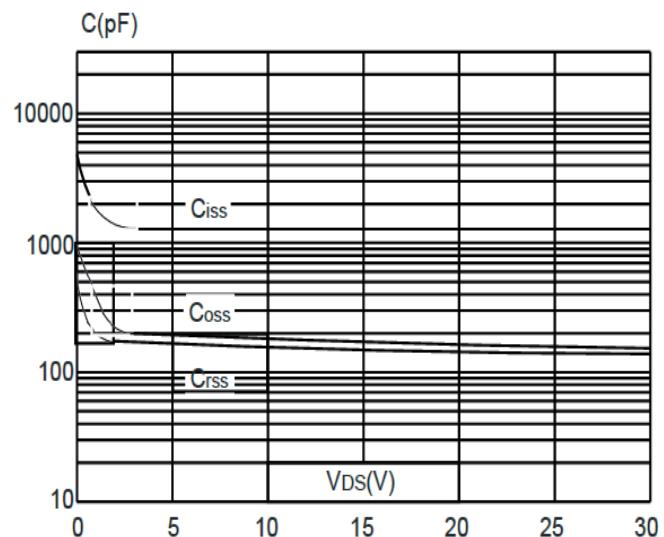
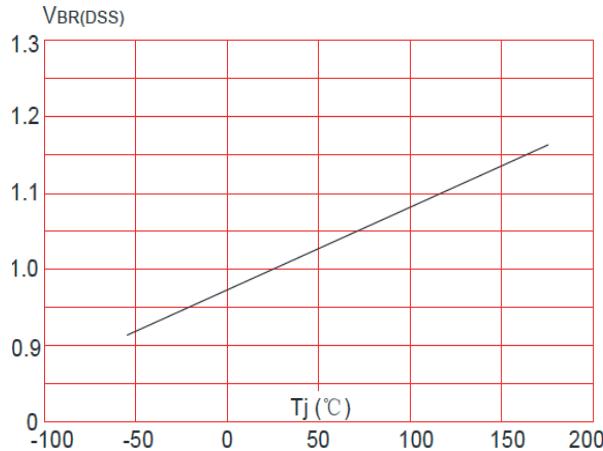


Figure 6: Capacitance Characteristics

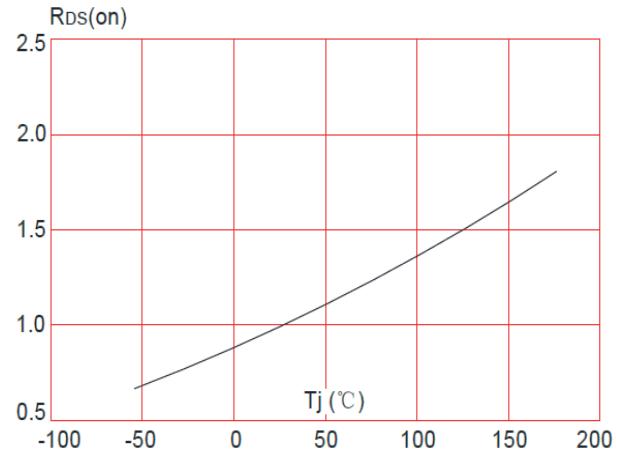


### Typical Performance Characteristics

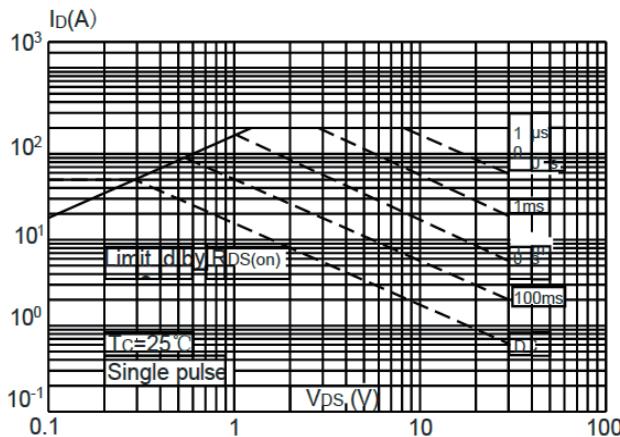
**Figure 7: Normalized Breakdown Voltage**



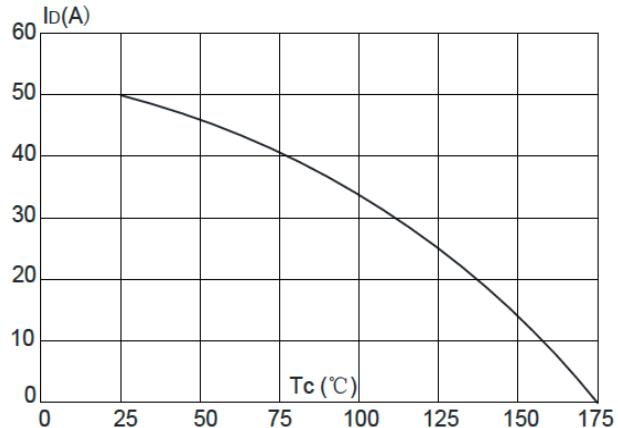
**Figure 8: Normalized on Resistance vs.  $J_A$**



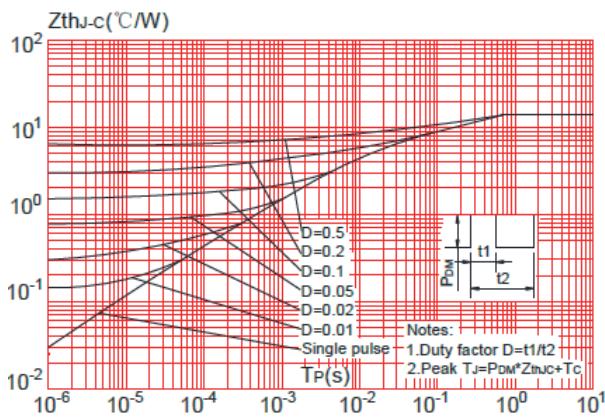
**Figure 9: Maximum Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current**



**Figure 11: Maximum Effective Transient Thermal Resistance**



## Test Circuit

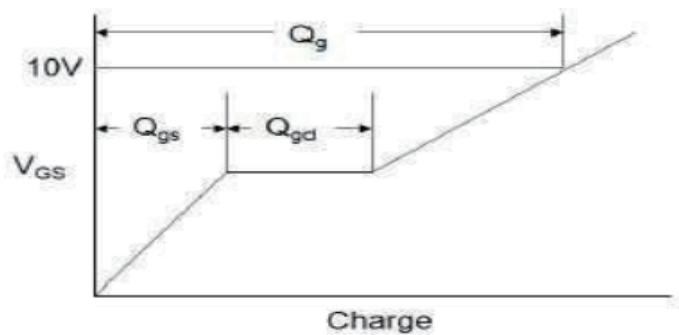
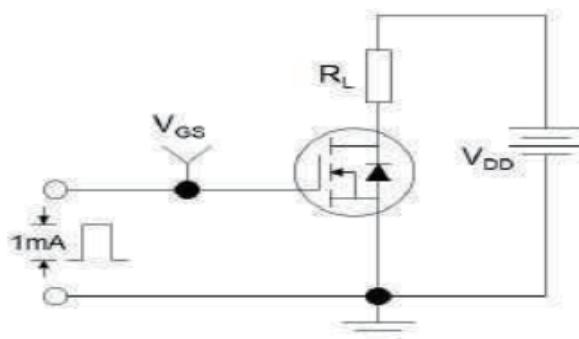


Figure 1: Gate Charge Test Circuit & Waveform

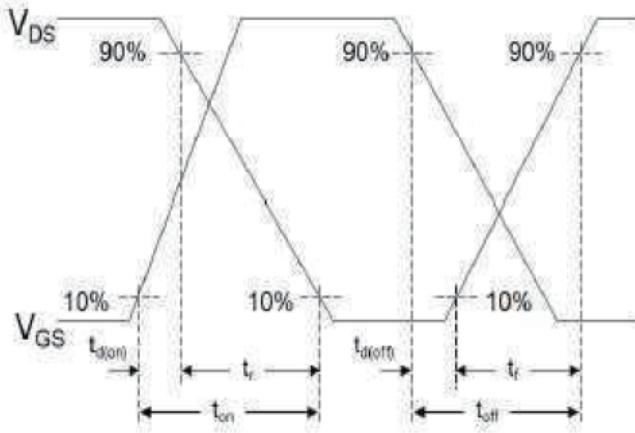
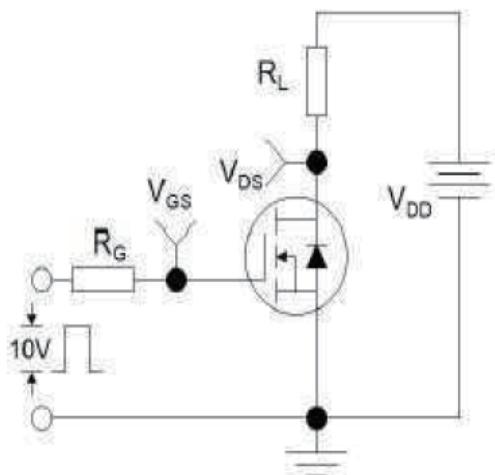


Figure 2: Resistive Switching Test Circuit & Waveforms

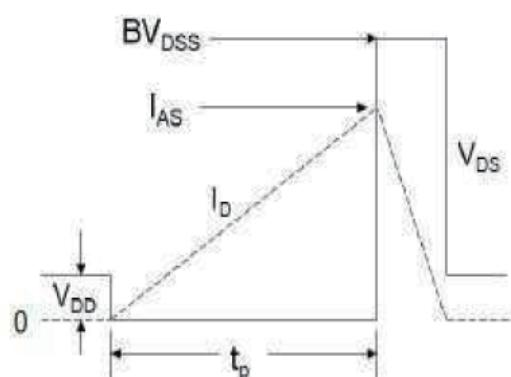
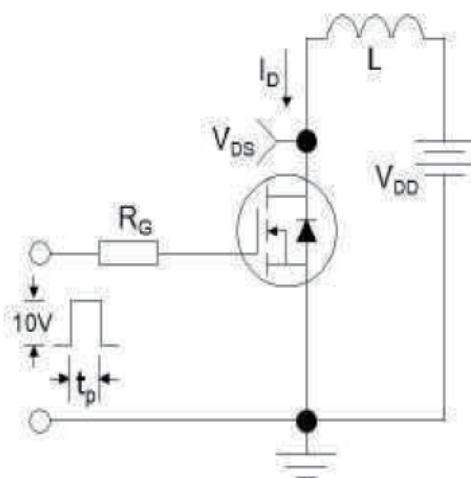
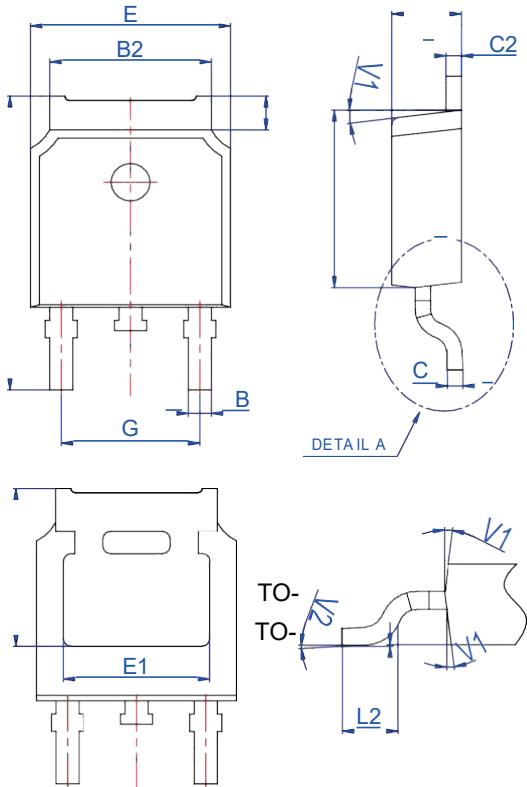


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

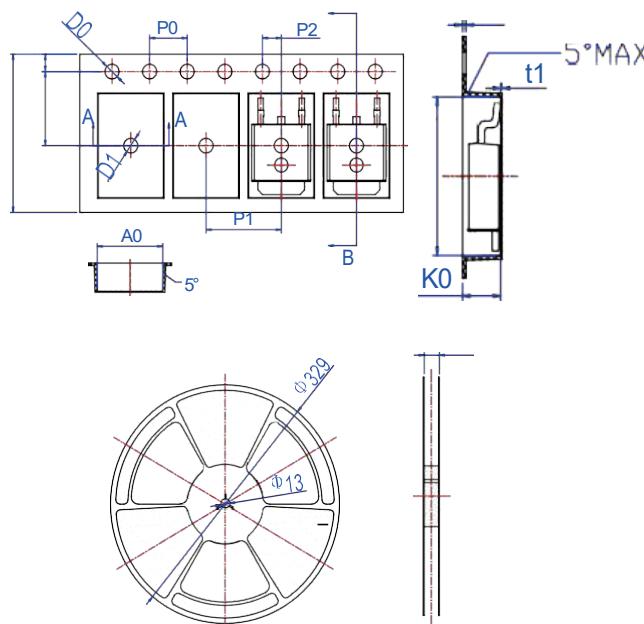


## Package Mechanical Data-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.1		2.5	0.083		0.098
A2	0		0.1	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.4		0.6	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.9		6.3	0.232		0.248
D1	5.30REF			0.209REF		
E	6.4		6.8	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.5		10.7	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1	7°			7°		
V2	0°			6°		

## Reel Specification-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.9	16	16.1	0.626	0.63	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.4	7.5	7.6	0.291	0.295	0.299
D0	1.4	1.5	1.6	0.055	0.059	0.063
D1	1.4	1.5	1.6	0.055	0.059	0.063
P0	3.9	4	4.1	0.154	0.157	0.161
P1	7.9	8	8.1	0.311	0.315	0.319
P2	1.9	2	2.1	0.075	0.079	0.083
A0	6.85	6.9	7	0.27	0.271	0.276
B0	10.45	10.5	10.6	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.1			0.004		
10P0	39.8	40	40.2	1.567	1.575	1.583